

Electronic supplementary information

Low-current field-assisted assembly of copper nanoparticles for current collectors

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This PDF file includes: Figures S1 to S7.

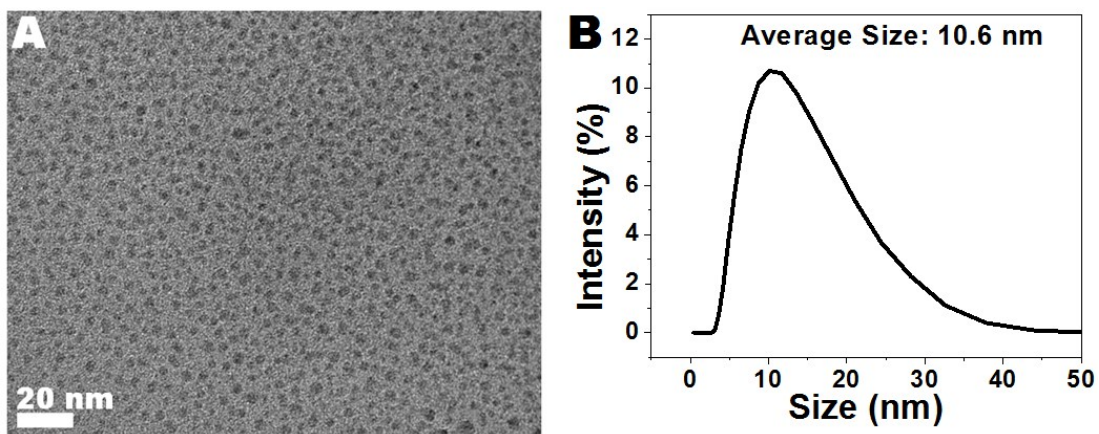


Fig. S1. (A) TEM image and (B) DLS size distribution of Cu NPs in dispersion. The larger size obtained in DLS data than in TEM images is attributed to the organic stabilizer shell and a relatively thick hydration layer.

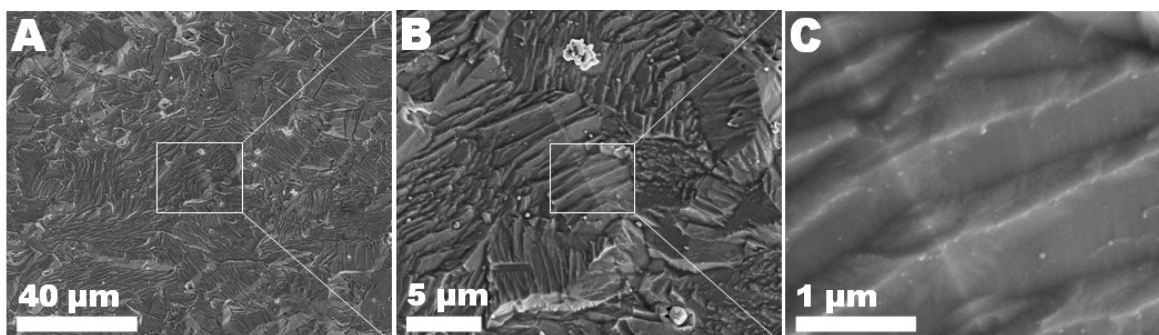


Fig. S2. (A-C) SEM images of Cu foil used for the preparation of NP-based film by field-stimulated assembly.

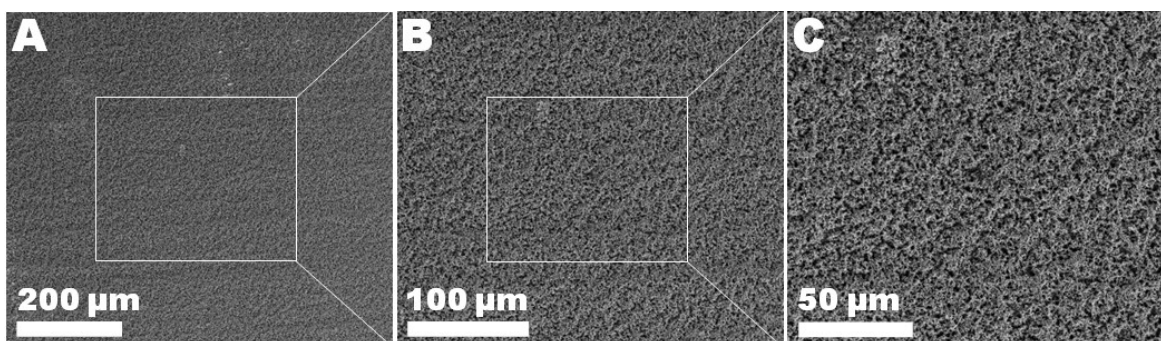


Fig. S3. (A-C) SEM images of 3D Cu film by field-stimulated assembly of Cu NPs at a potential of 2000 mV (current: ~ 75 mA) for 8 min.

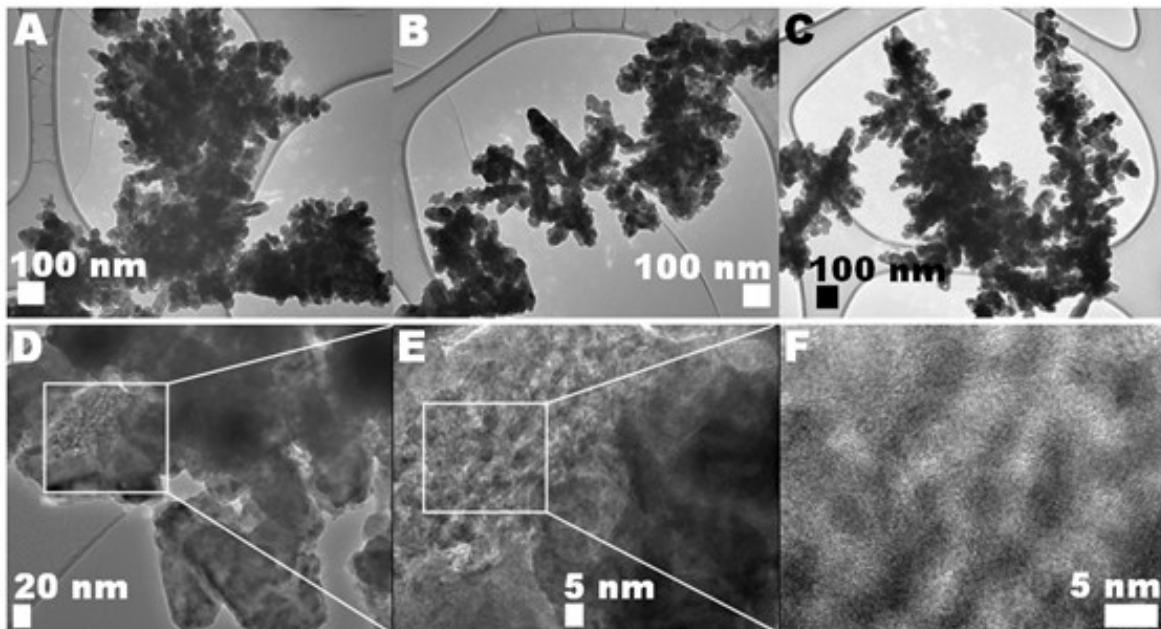


Fig. S4. (A-F) TEM images of the dendrites formed from Cu NPs during the field-stimulated assembly under a potential of 2000 mV (current: ~ 75 mA) for 8 min.

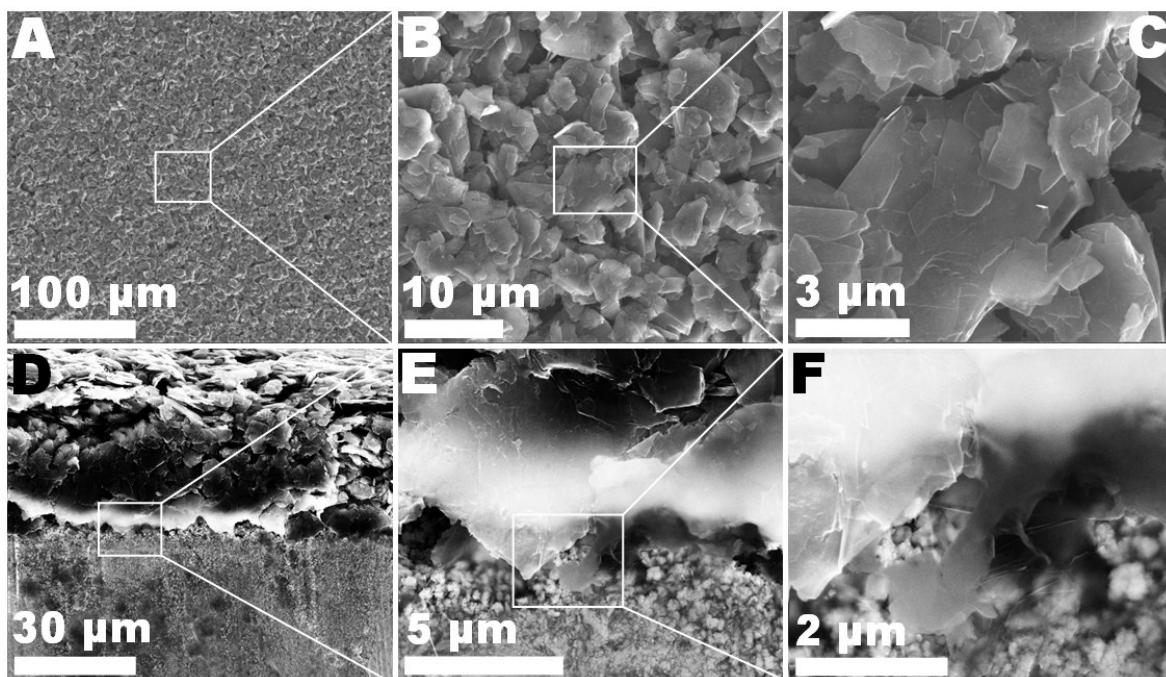


Fig. S5. (A-C) Top-view and (D-F) cross-sectional SEM images of dried graphite (~ 3 mg) slurry coating on NP-based Cu current collector prepared under a potential of 2000 mV (current: ~ 75 mA) for 8 min.

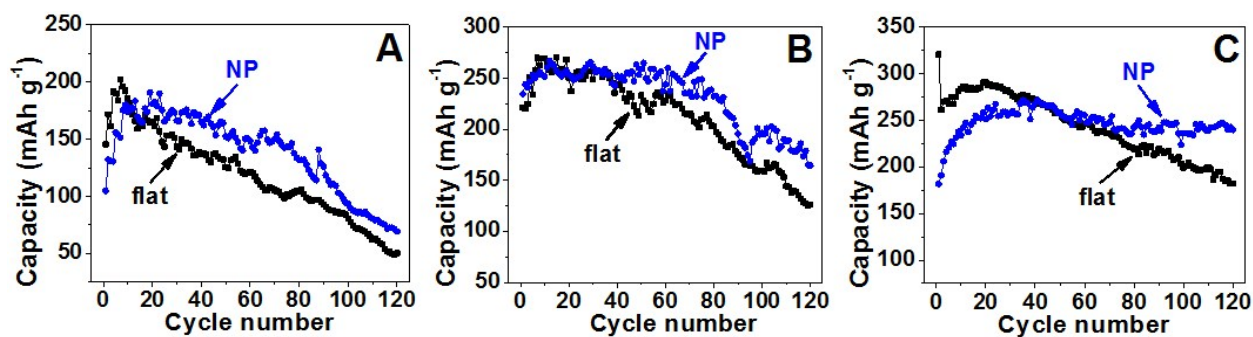


Fig. S6. Cycle performance of (A) 11.5, (B) 7.0 and (C) 3.0 mg graphite on flat and NP-based Cu electrodes at 0.25 C rate, respectively.

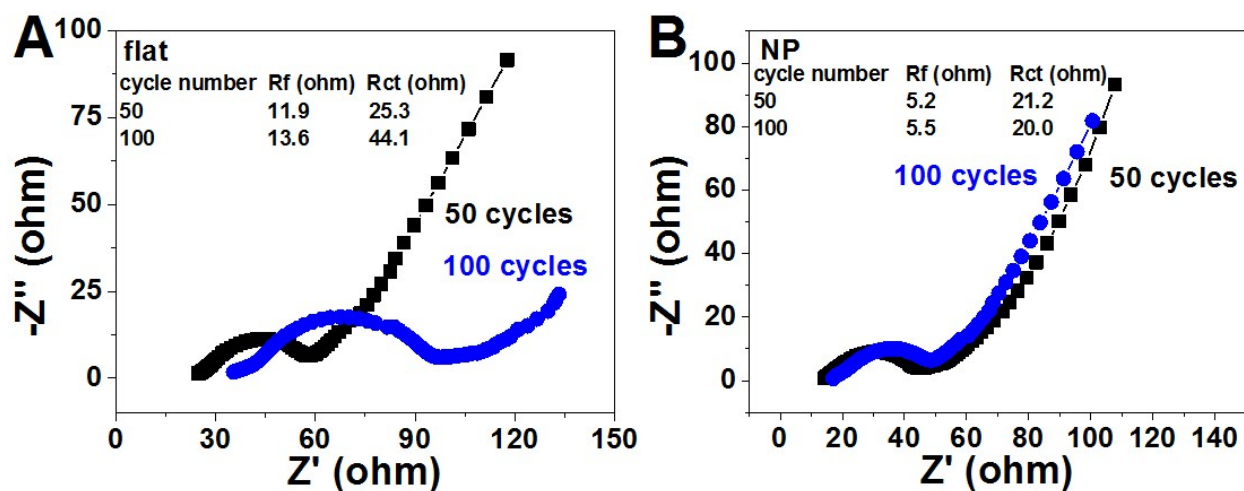


Fig. S7. Impedance spectra of (A) flat and (B) NP-based Cu current collectors after 50 and 100 charge-discharge cycles at 0.25 C rate with 7.0 mg graphite loading.